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B41J 2/16

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B6F FLP

(56) Documents Cited

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(58) Field of Search

UK CL (Edition V) B6F

INT CL⁷ B41J

Other: Online: EPODOC JAPIO WPI

(54) Abstract Title

Substrate and method of forming substrate for fluid ejection device

(57) A method of forming an opening (50/50'/150/150') through a substrate (60) includes etching into the substrate from a first side (62) so as to form a first portion (52/152) of the opening, etching into the substrate from a second side (64) opposite the first side so as to form a second portion (54/154) of the opening, continuing etching into the substrate from at least one of the first side and the second side toward the other of the first side and the second side so as to communicate the first portion and the second portion of the opening, and etching into the substrate from an interface (55/155) between the first portion and the second portion of the opening, including etching toward the second side of the substrate and forming a third portion (56/56'/156) of the opening. There is also a substrate (60) for a fluid ejection device having a fluidic channel (50) formed by the method described above. The fluid ejection device may be an inkjet printhead.

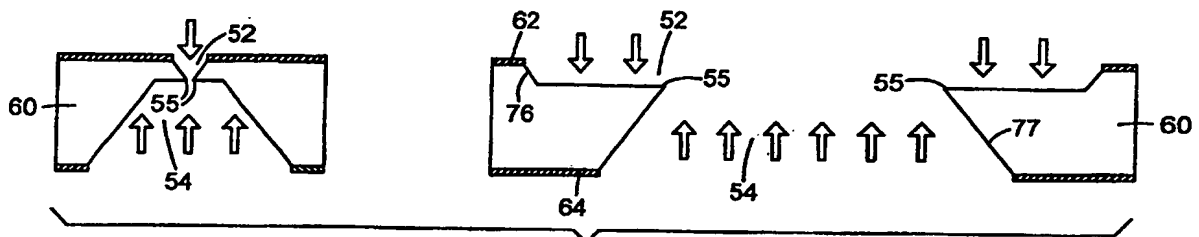


Fig. 5C

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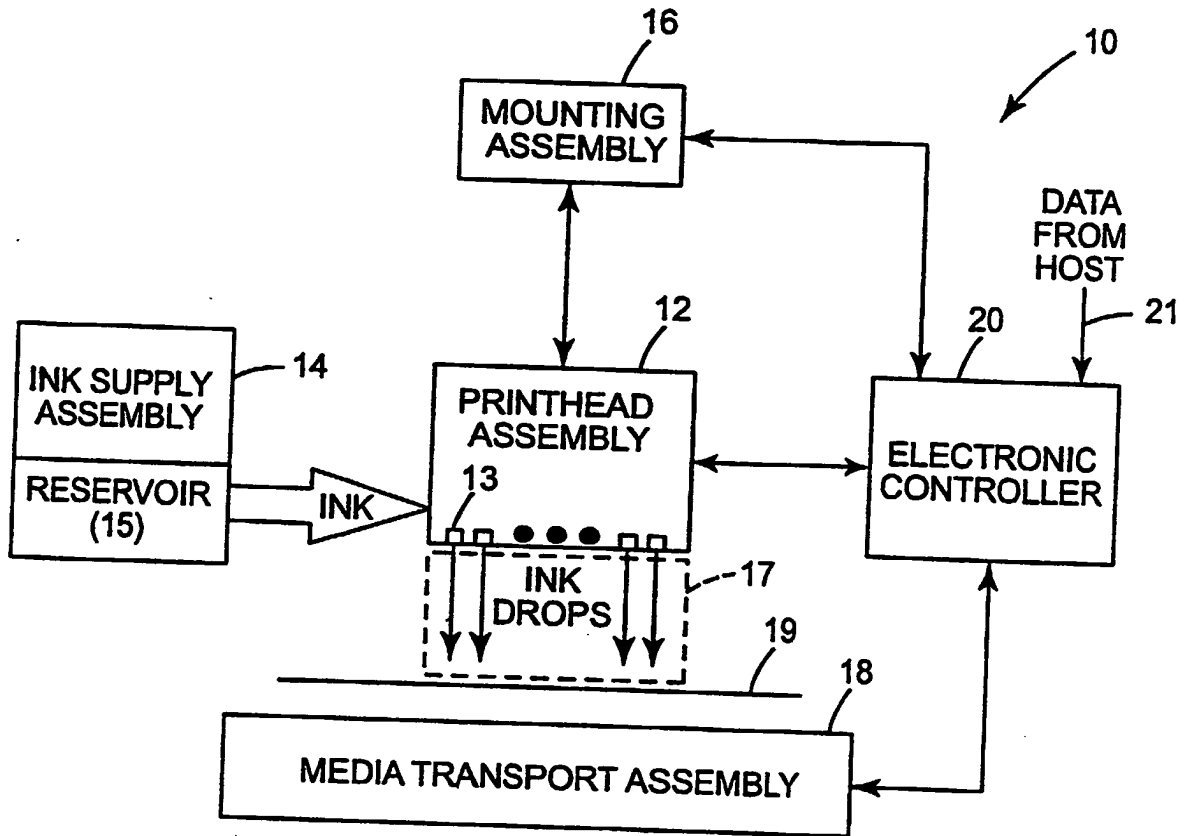


Fig. 1

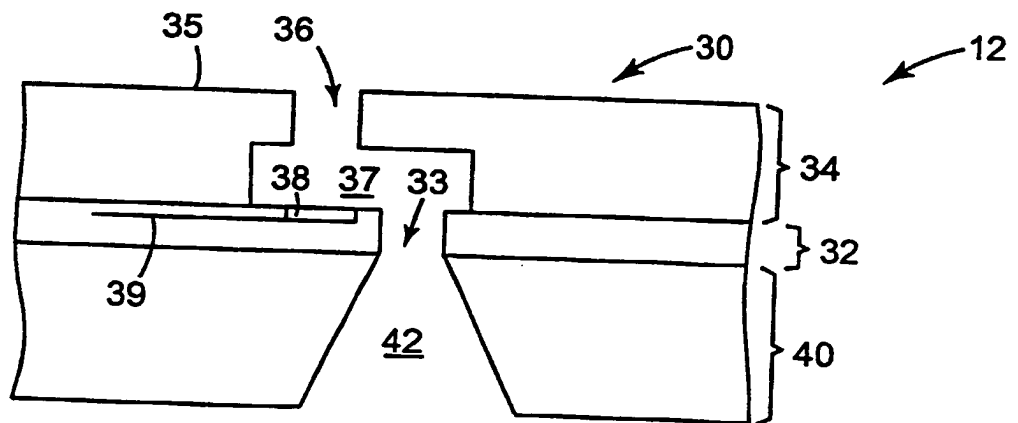


Fig. 2

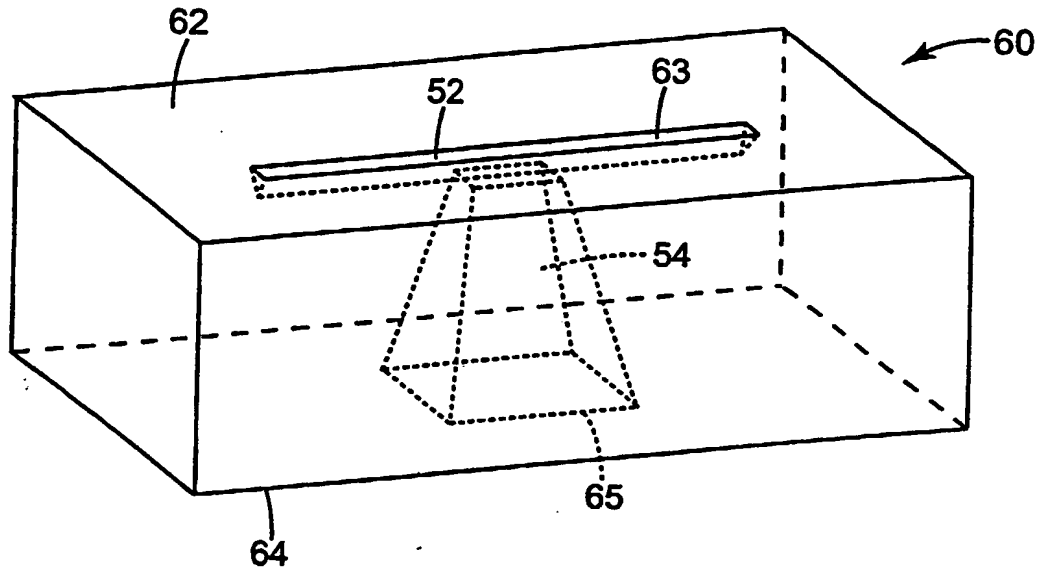


Fig. 3A

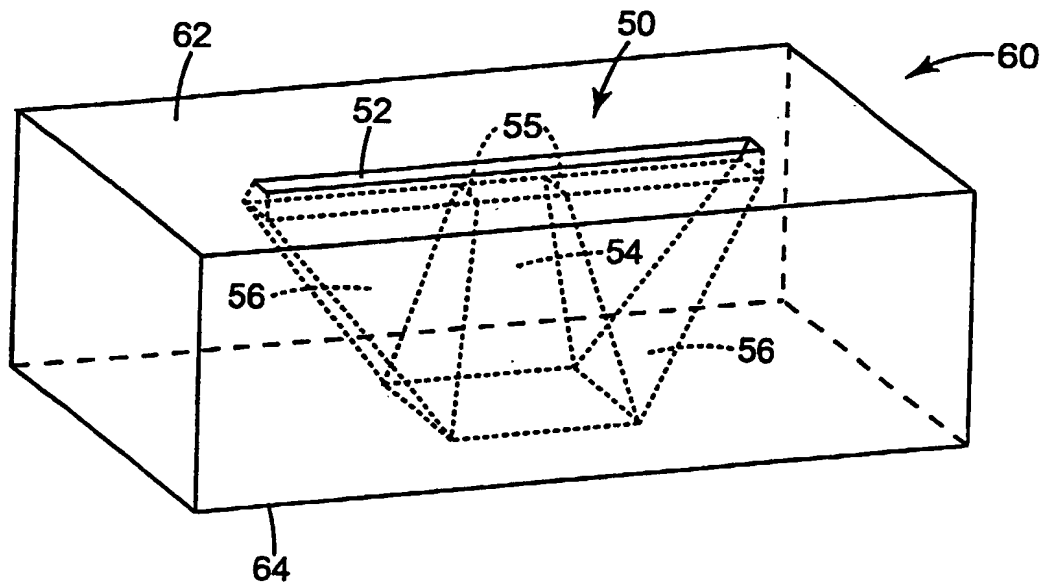


Fig. 3B

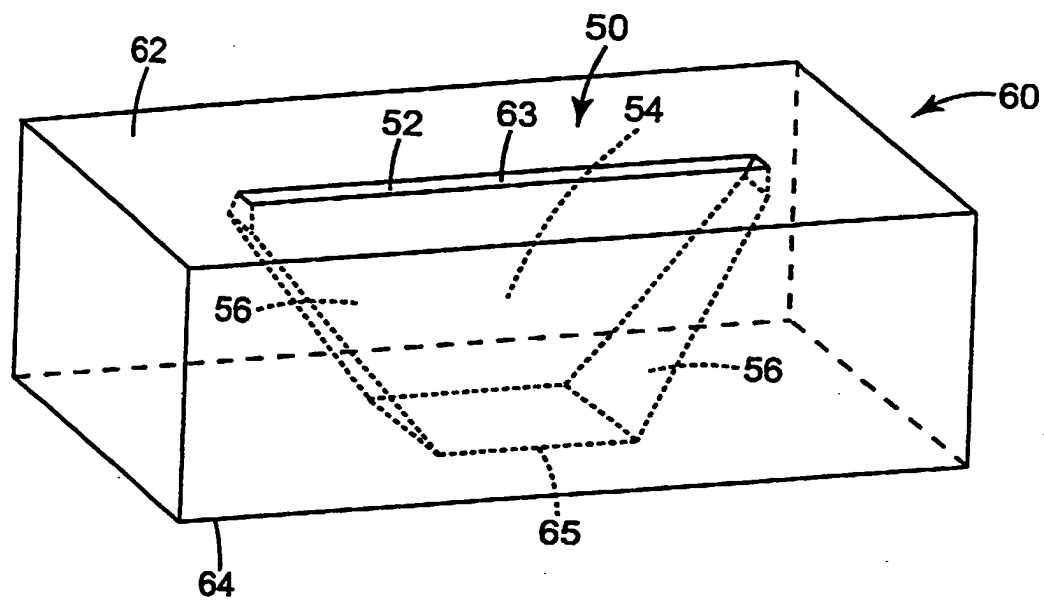


Fig. 3C

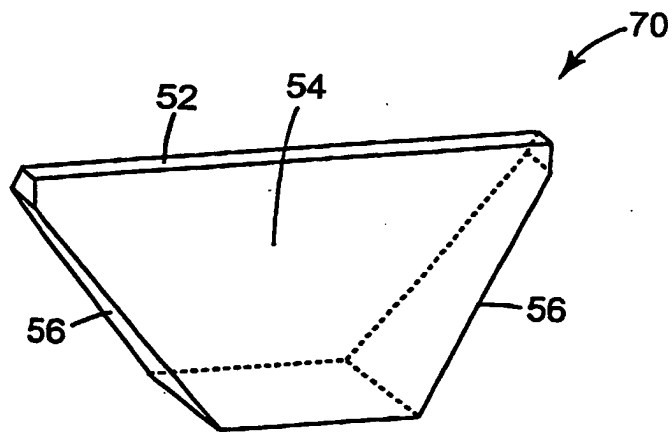


Fig. 3D

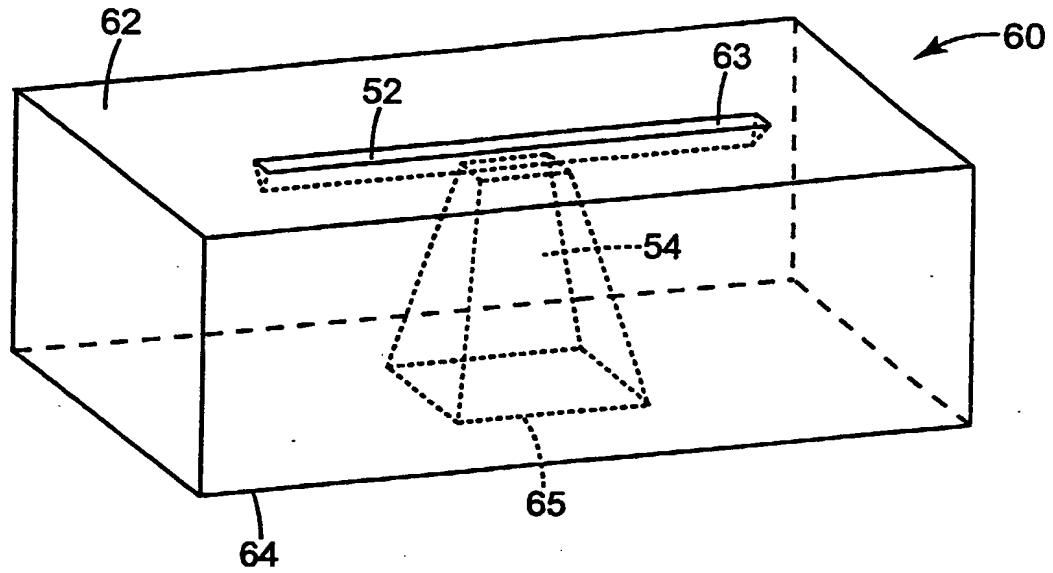


Fig. 4A

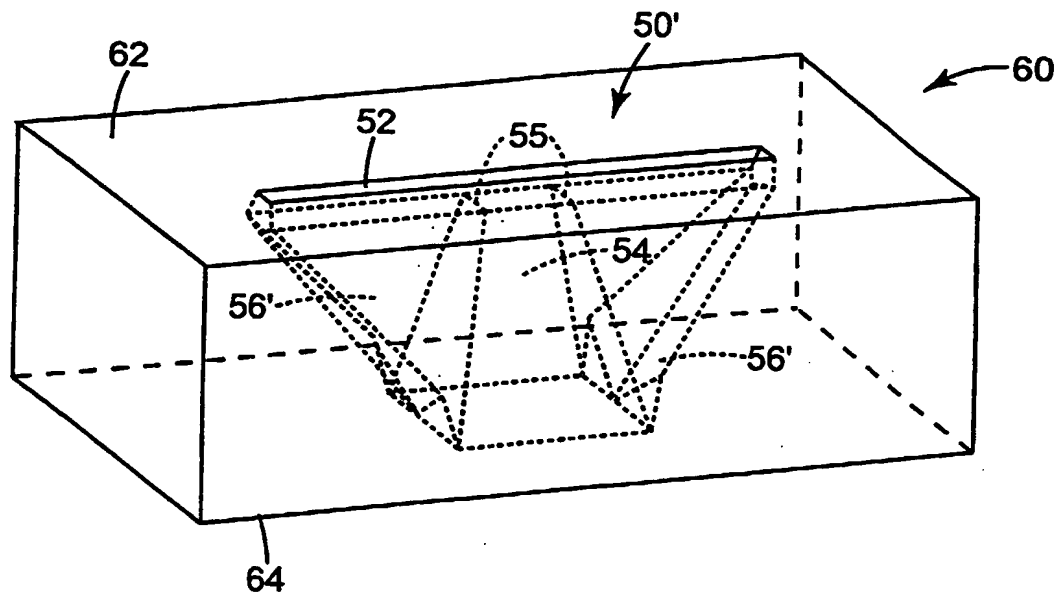


Fig. 4B

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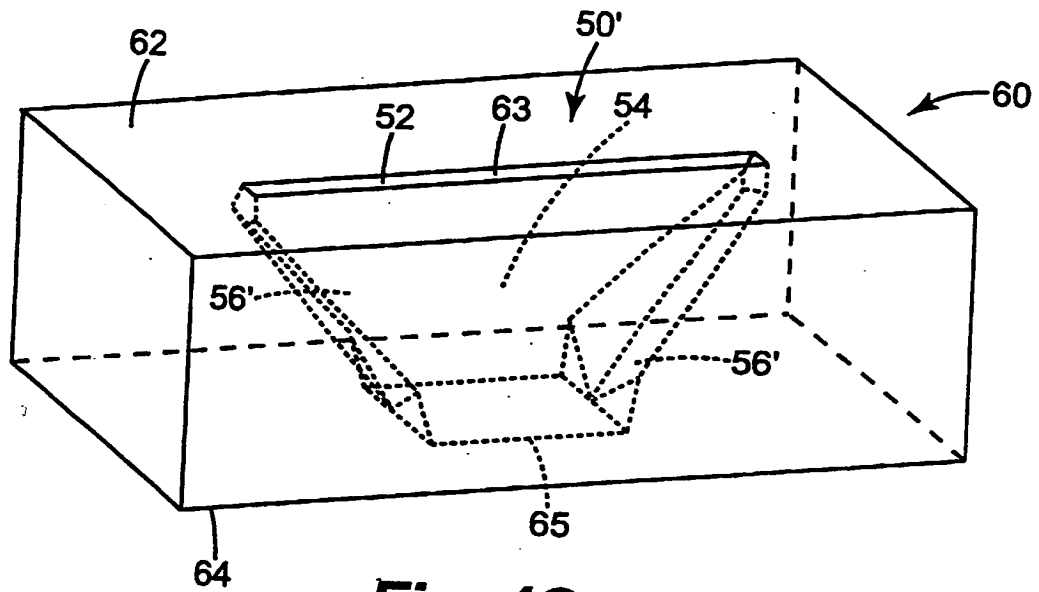


Fig. 4C

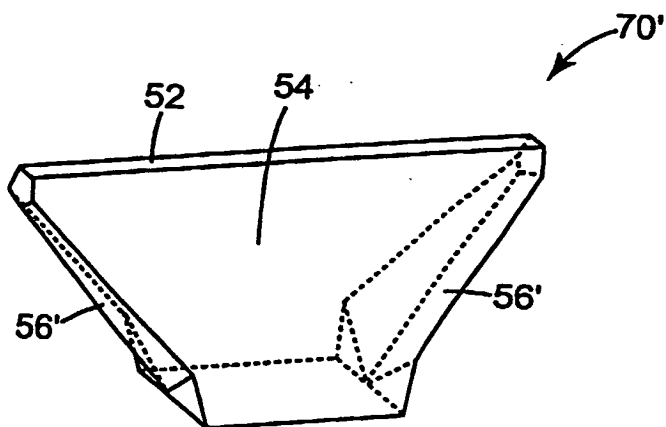


Fig. 4D

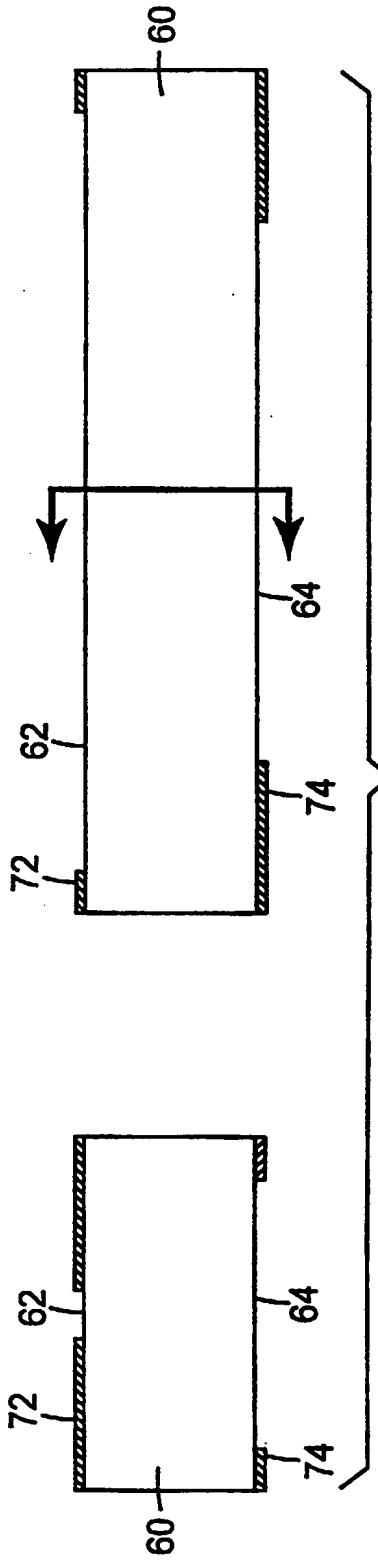


Fig. 5A

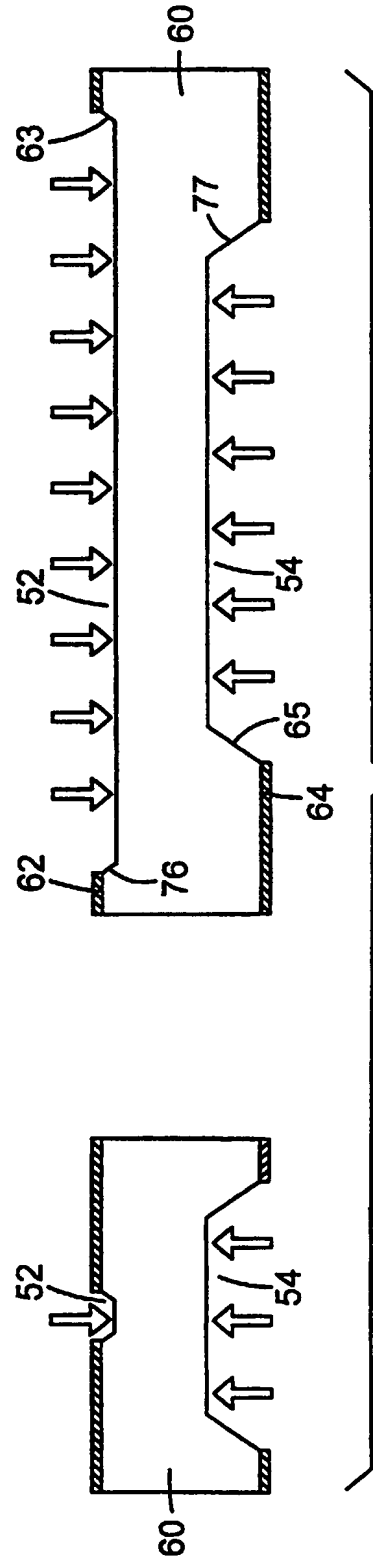


Fig. 5B

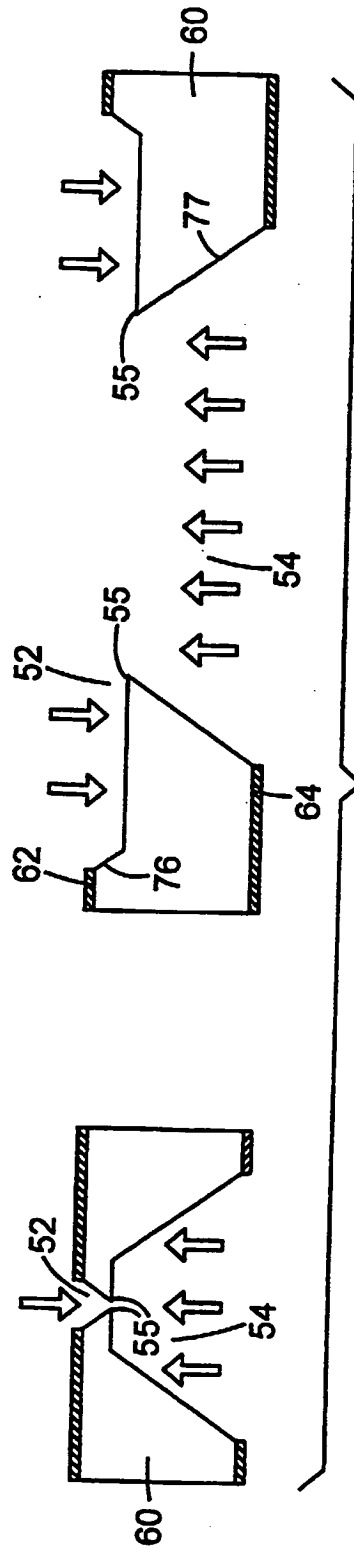


Fig. 5C

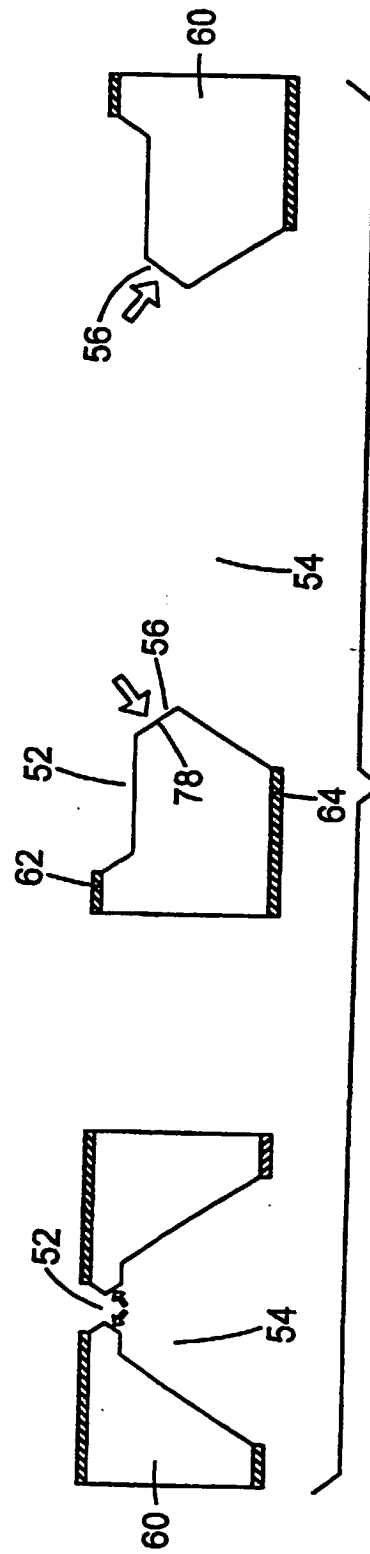


Fig. 5D

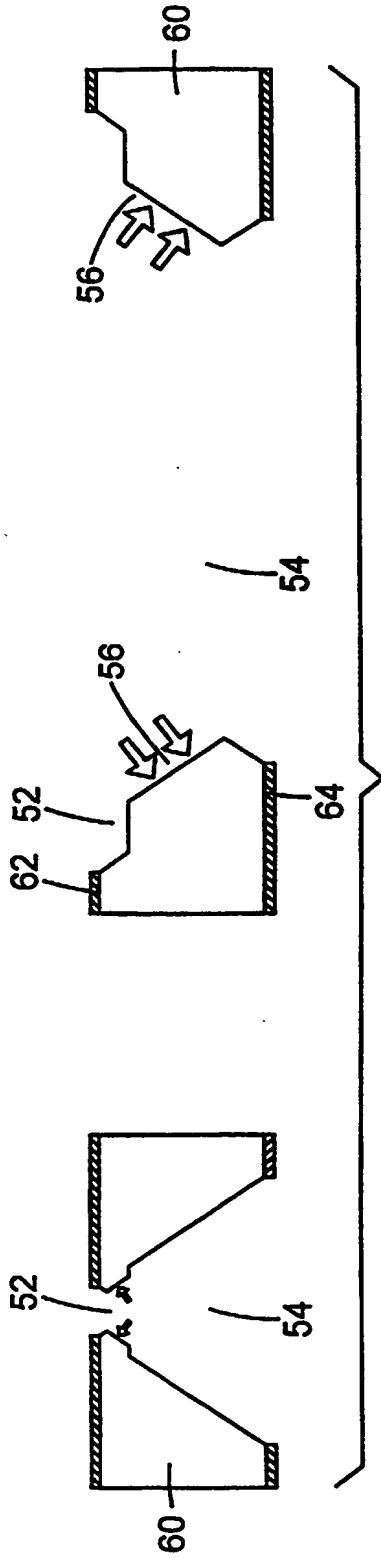


Fig. 5E

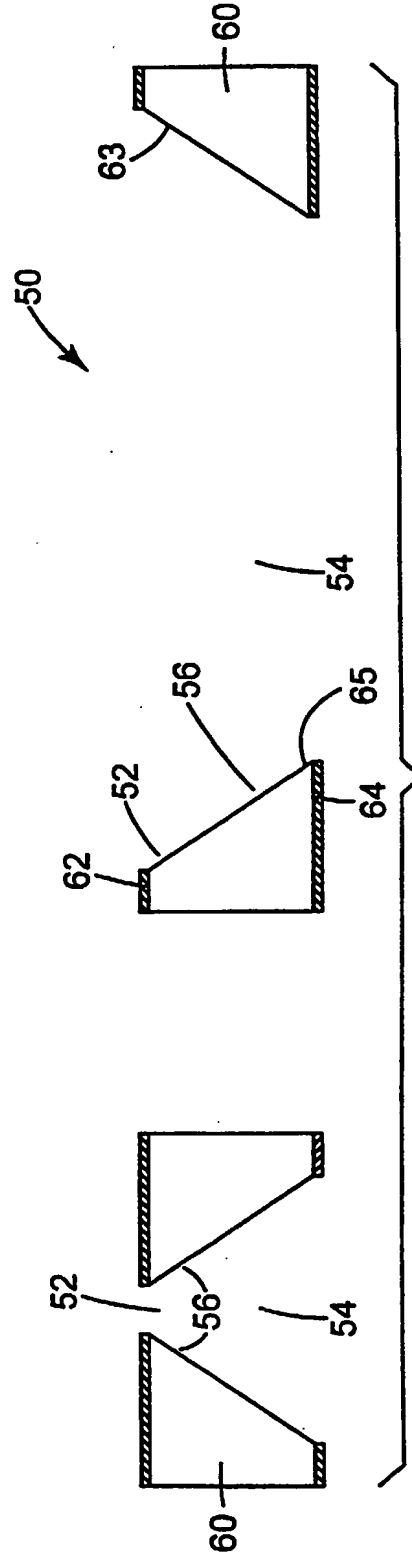


Fig. 5F

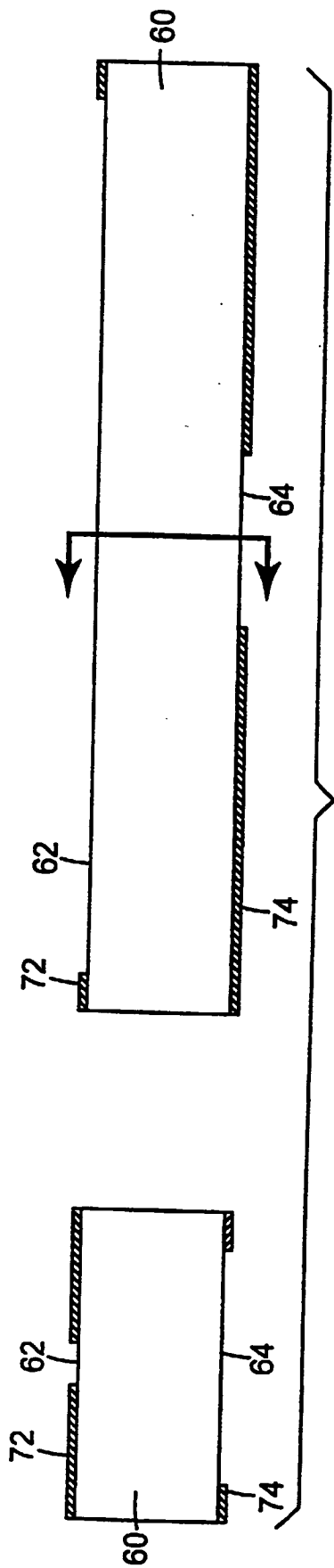


Fig. 6A

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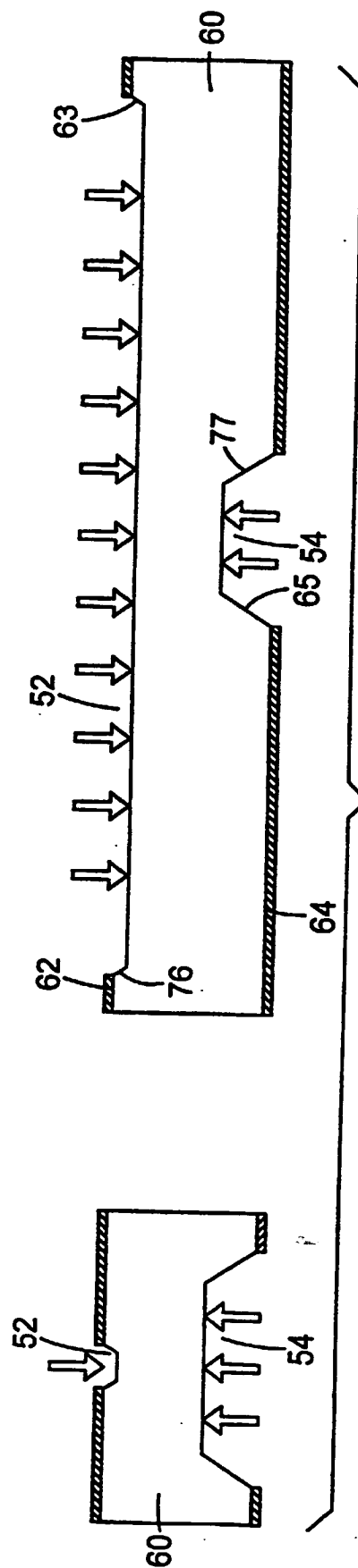


Fig. 6B

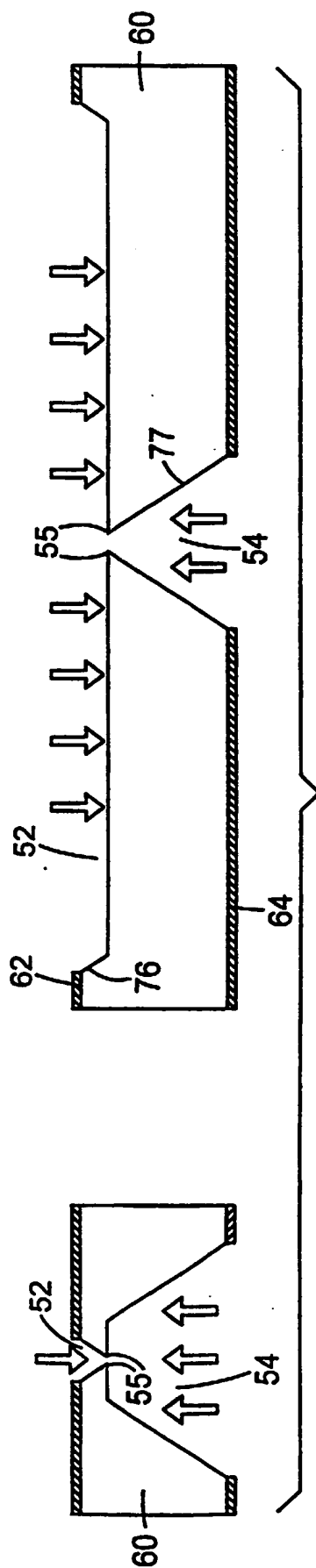


Fig. 6C

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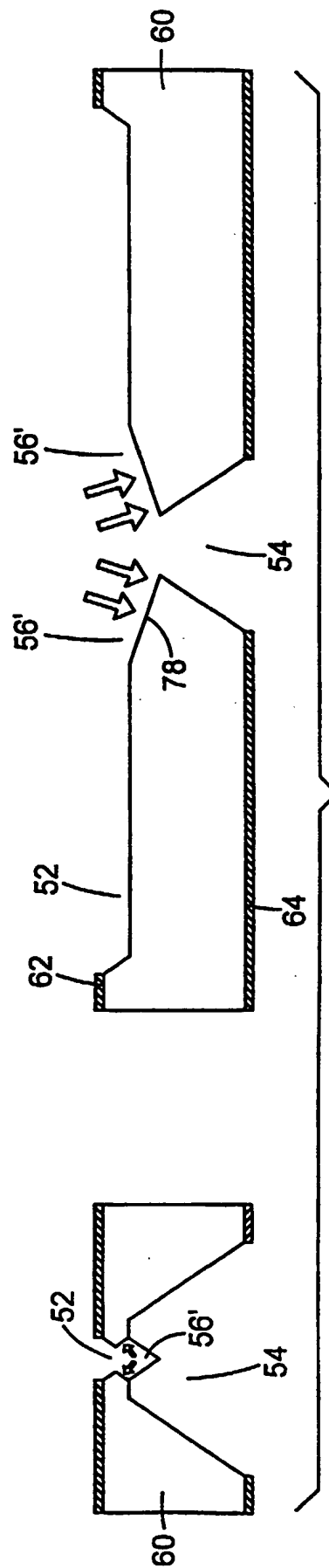


Fig. 6D



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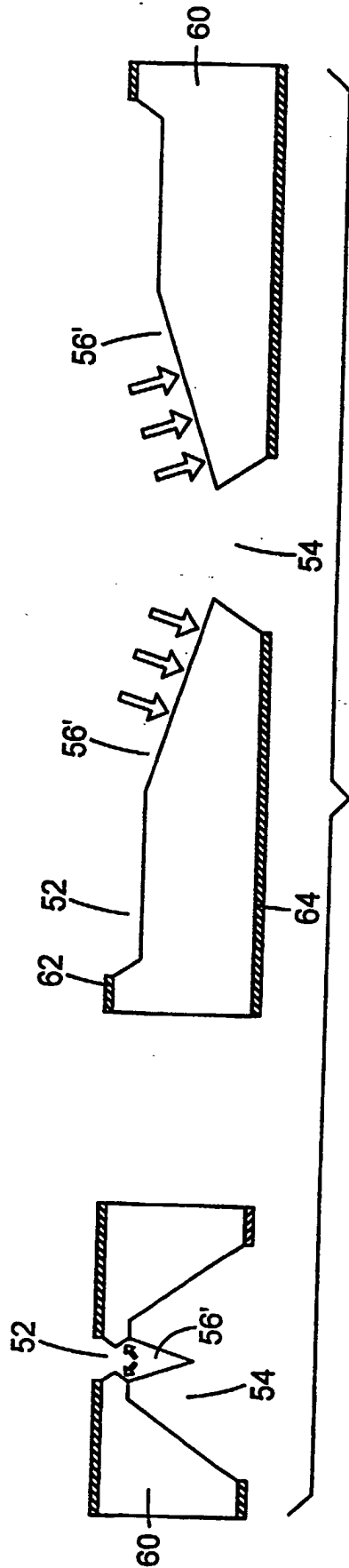


Fig. 6E

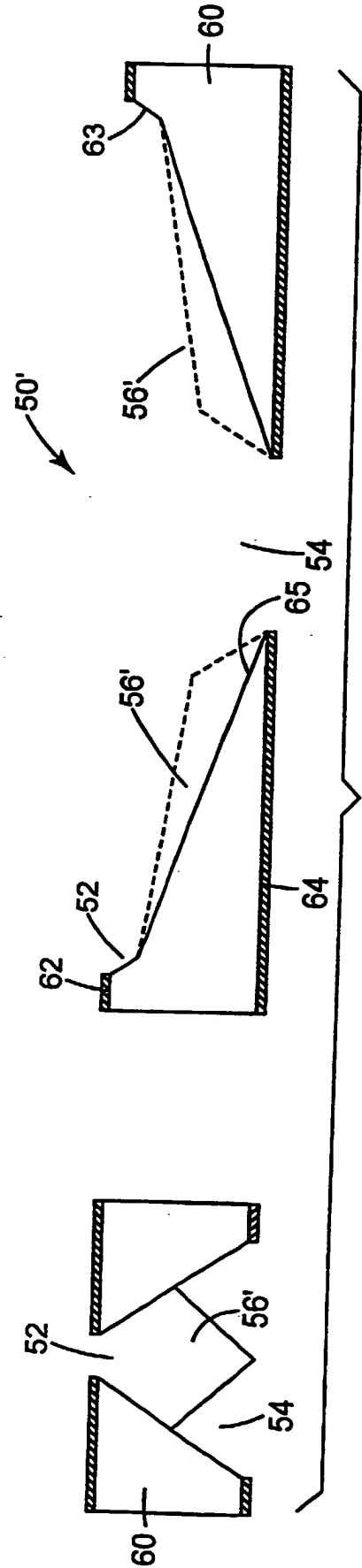


Fig. 6F

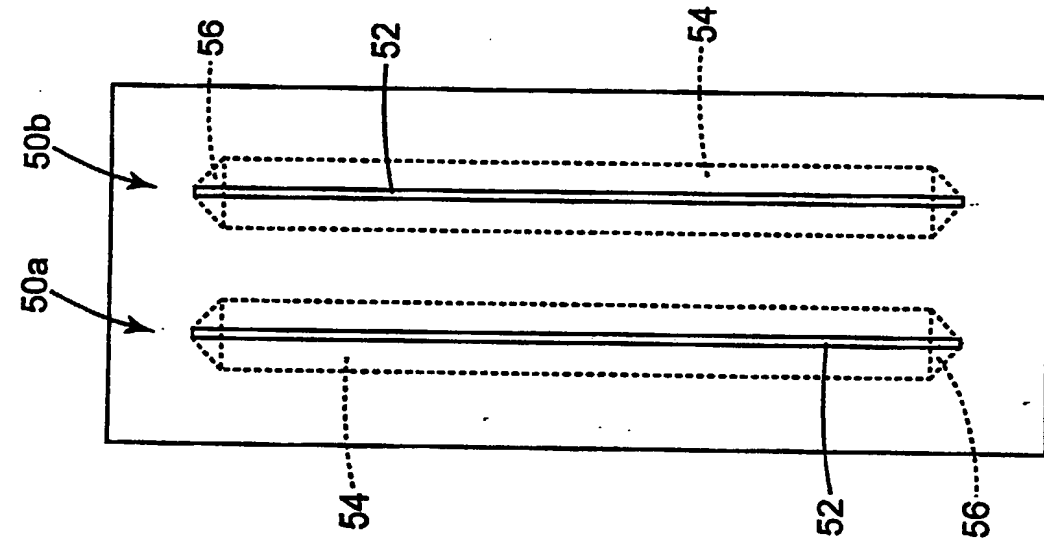


Fig. 8

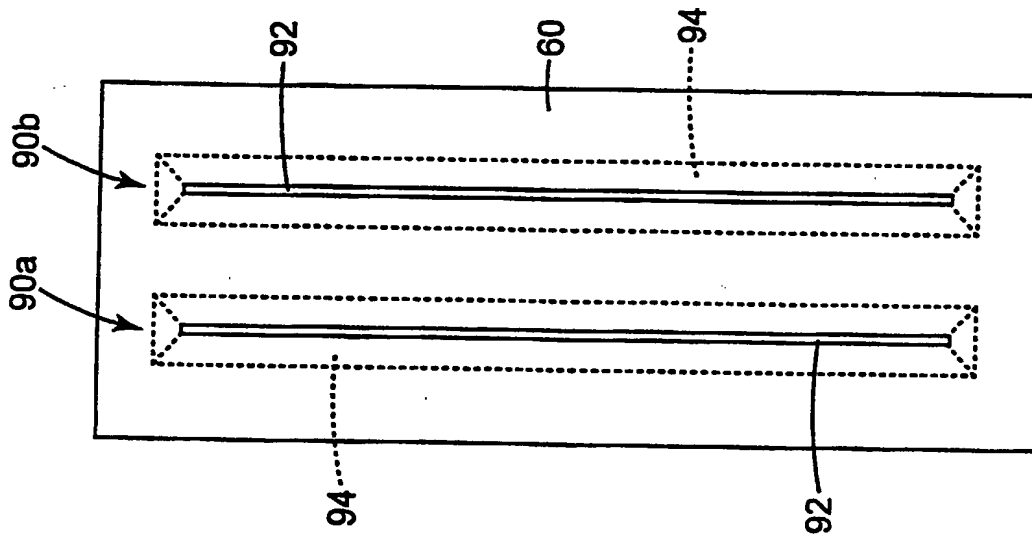


Fig. 7
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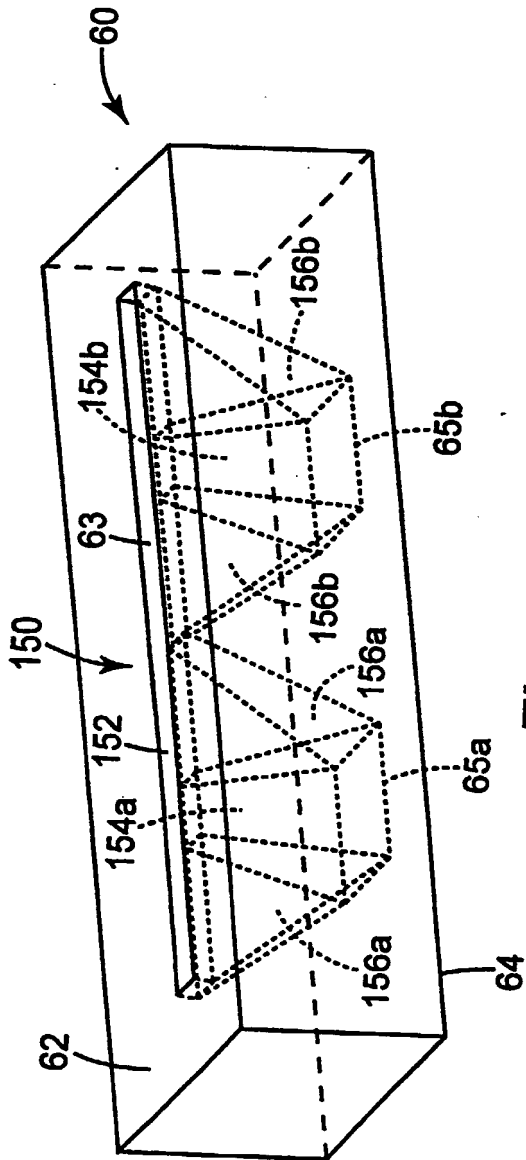


Fig. 9A

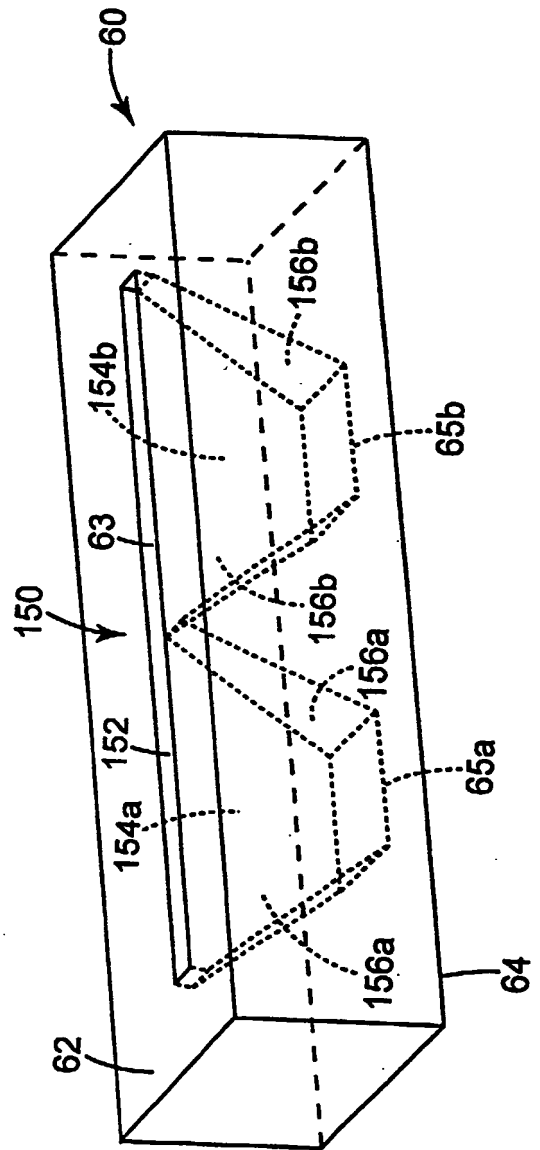


Fig. 9B

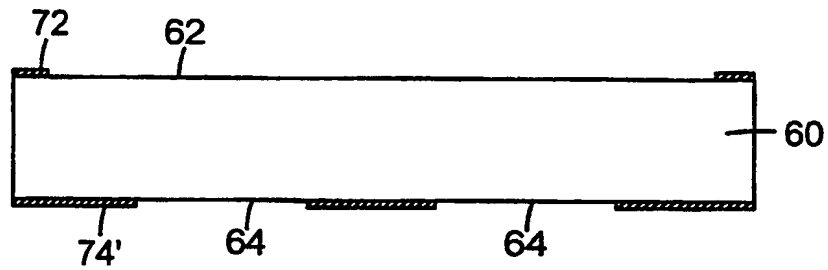


Fig. 10A

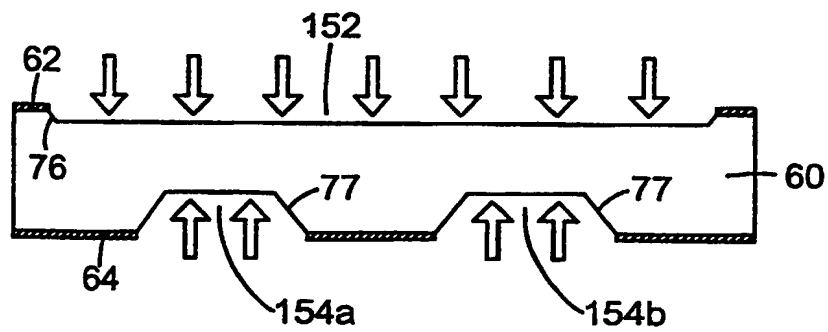


Fig. 10B

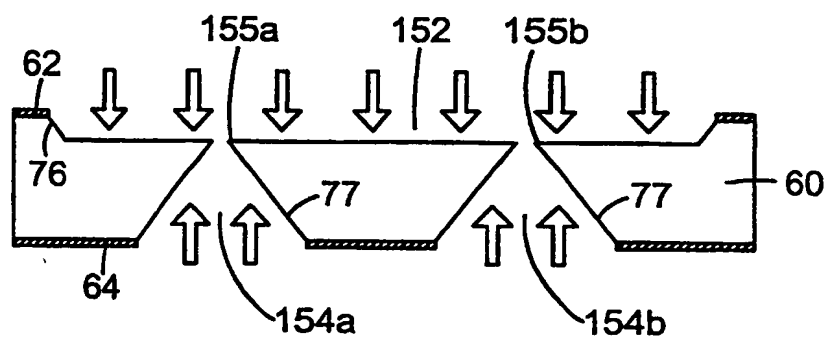


Fig. 10C

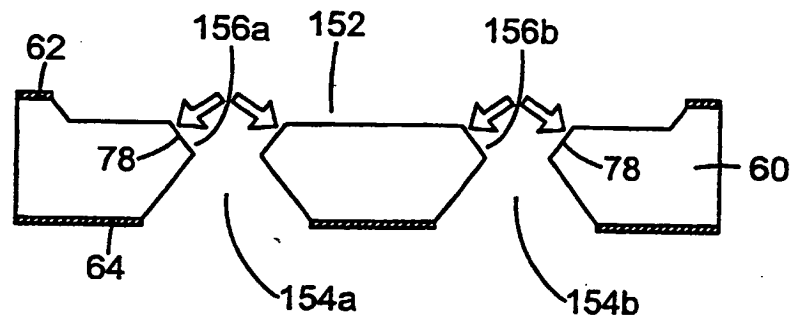


Fig. 10D

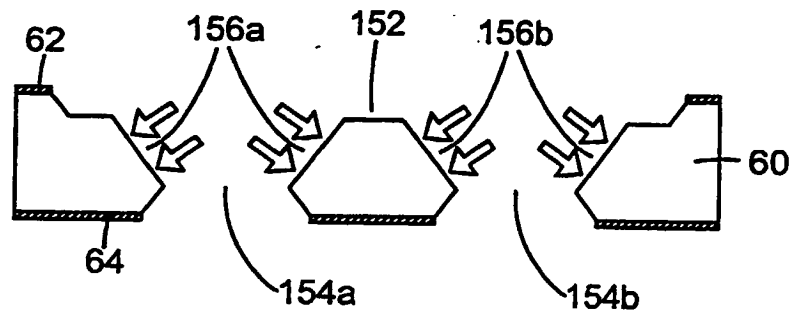


Fig. 10E

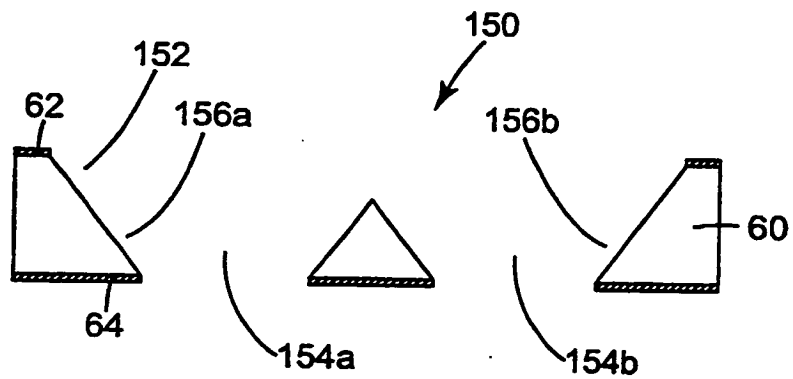
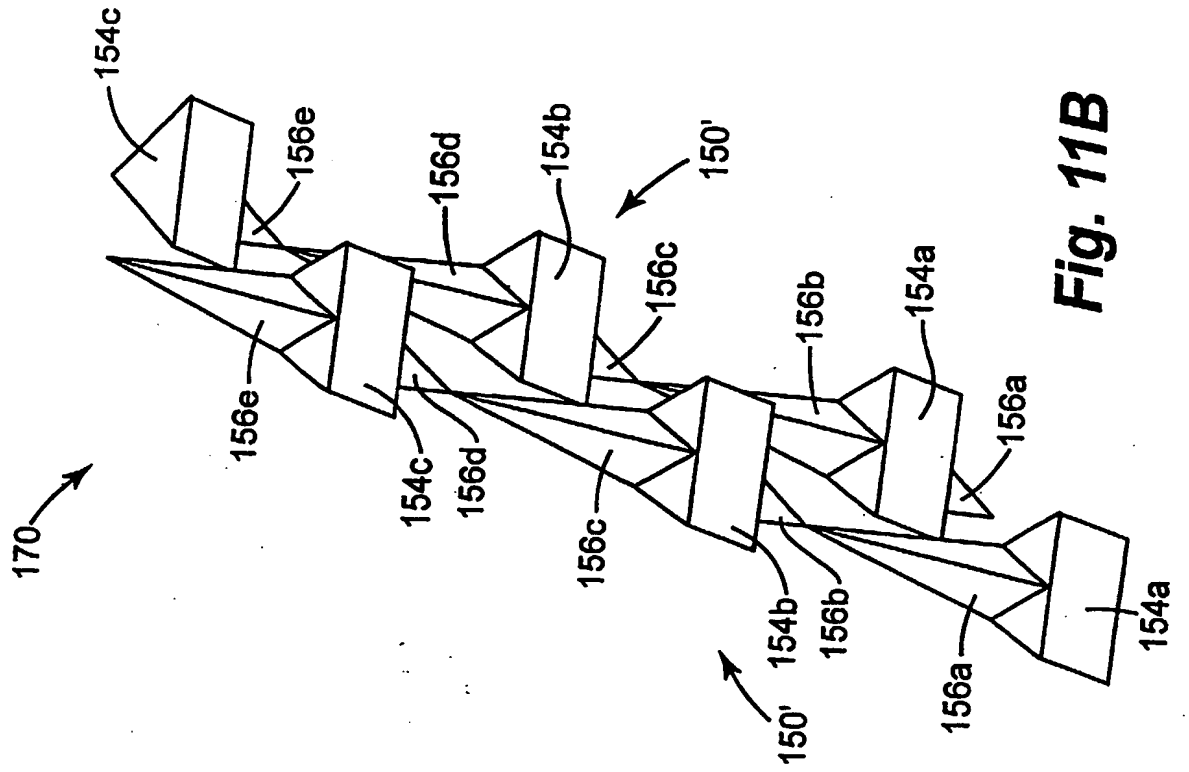
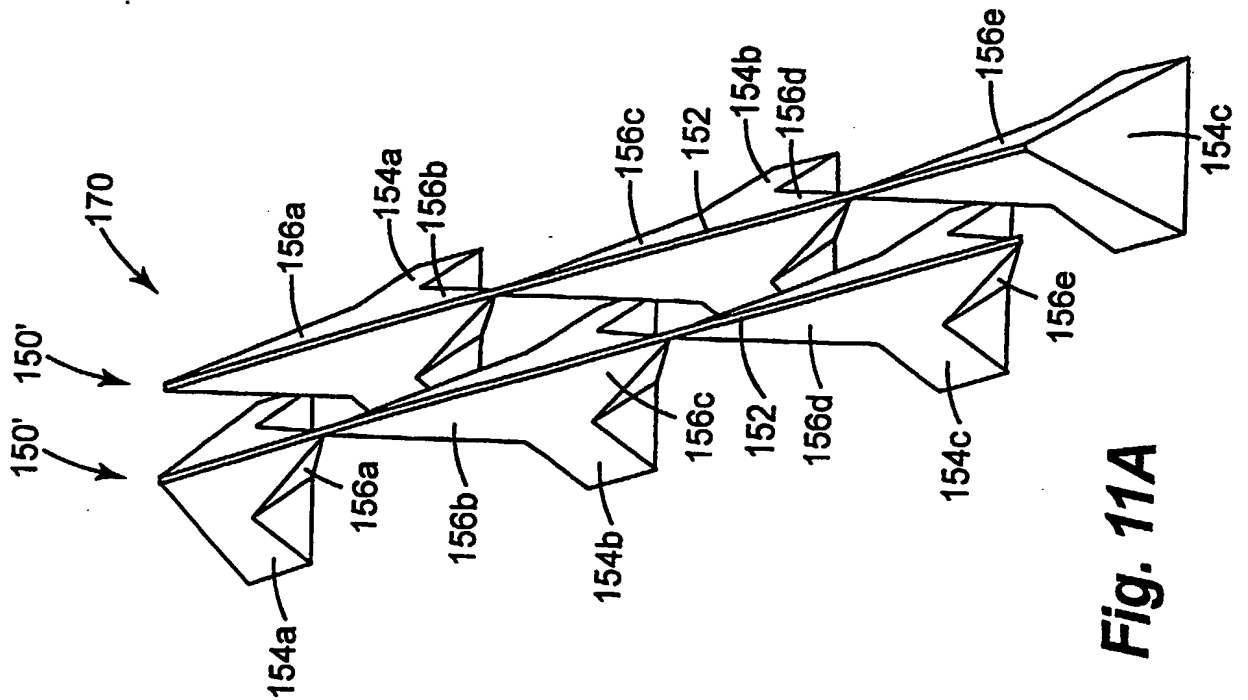


Fig. 10F



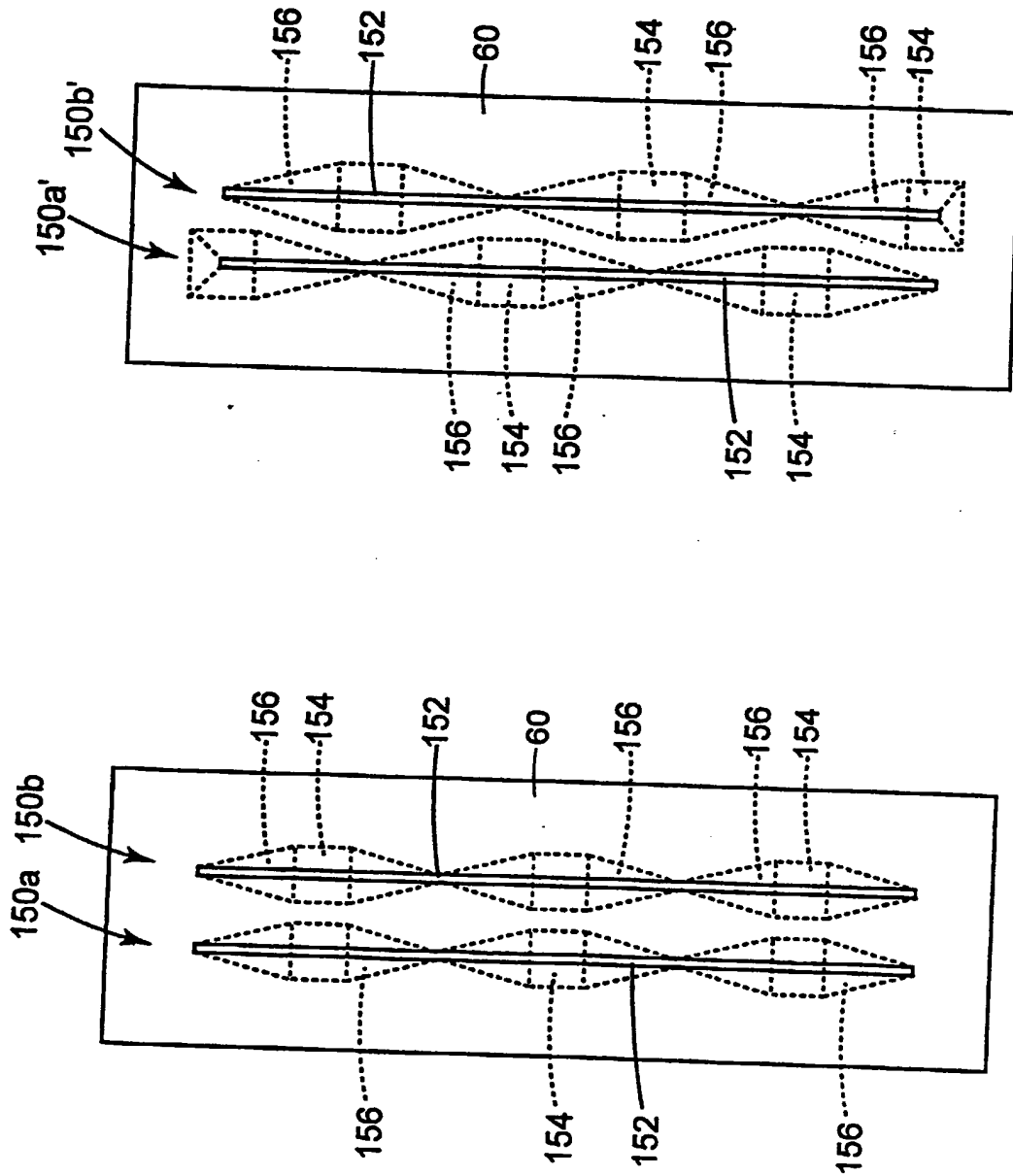


Fig. 13

Fig. 12